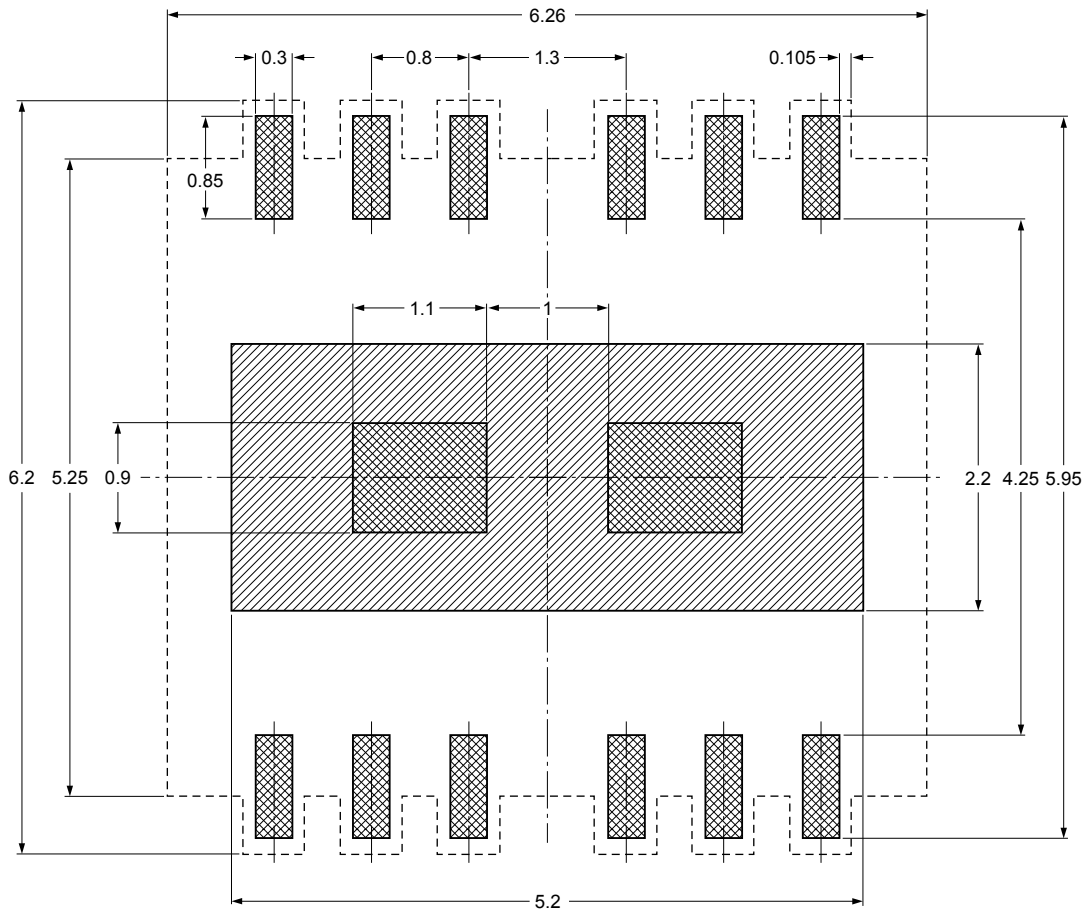






Footprint information for reflow soldering of HVSON12 package

SOT1352-1



-  occupied area
-  solder resist
-  solder lands
-  solder paste

Dimensions in mm

Issue date ~~13-05-14~~
13-06-04

sot1352-1_fr